

0.8A, 200V - 1000V High Efficient Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

MECHANICAL DATA

• Case: SOD-123W

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

 Meet JESD 201 class 2 whisker test Polarity: Indicated by cathode band

• Weight: 0.016g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	0.8	Α	
V_{RRM}	200 - 1000	٧	
I _{FSM}	20	Α	
T _{J MAX}	150	°C	
Package	SOD-123W		
Configuration	Single die		









SOD-123W



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)							
PARAMETER	SYMBOL	HSDLW	HSGLW	HSJLW	HSKLW	HSMLW	UNIT
Marking code on the device		HSDLW	HSGLW	HSJLW	HSKLW	HSMLW	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	V _{R(RMS)}	140	280	420	560	700	V
Forward current	I _F			0.8			Α
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	20		А			
Junction temperature	T_J	- 55 to +150		°C			
Storage temperature	T _{STG}	- 55 to +150			°C		



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	34	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	86	°C/W	
Junction-to-case thermal resistance	$R_{ heta JC}$	35	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		$I_F = 0.4A, T_J = 25^{\circ}C$		0.81	0.97	V
	HSDLW	I _F = 0.8A, T _J = 25°C		0.86	1.00	V
		I _F = 0.4A, T _J = 125°C		0.66	0.79	V
		I _F = 0.8A, T _J = 125°C		0.73	0.83	V
		$I_F = 0.4A, T_J = 25^{\circ}C$	-	0.84	1.01	V
(1)		I _F = 0.8A, T _J = 25°C	=	0.91	1.30	V
Forward voltage ⁽¹⁾	HSGLW	I _F = 0.4A, T _J = 125°C	V_{F}	0.70	0.83	V
		I _F = 0.8A, T _J = 125°C	-	0.77	1.05	V
		I _F = 0.4A, T _J = 25°C		1.17	1.40	V
	HSJLW	I _F = 0.8A, T _J = 25°C		1.31	1.70	V
	HSKLW	I _F = 0.4A, T _J = 125°C		0.93	1.12	V
	HSMLW	I _F = 0.8A, T _J = 125°C		1.09	1.30	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C		-	1	μΑ
		T _J = 125°C	- I _R	-	150	μA
	HSDLW		CJ	17	-	pF
	HSGLW	-		14	-	pF
Junction capacitance	HSJLW	1MHz, V _R = 4.0V				
	HSKLW			5	-	pF
	HSMLW					
	HSDLW		t _{rr}		50	
Reverse recovery time	HSGLW	$I_F = 0.5A$, $I_R = 1.0A$		-	50	ns
	HSJLW					
	HSKLW	$I_{rr} = 0.25A$		-	75	ns
	HSMLW					

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
HSxLW	SOD-123W	10,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 200V(HSDLW) to 1000V(HSMLW)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

1.0 (¥) 0.8 HNAPO 0.6 0.4 US 50 75 100 125 150 LEAD TEMPERATURE (°C)

Fig.2 Typical Junction Capacitance

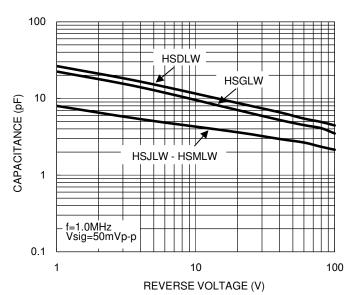


Fig.3 Typical Reverse Characteristics

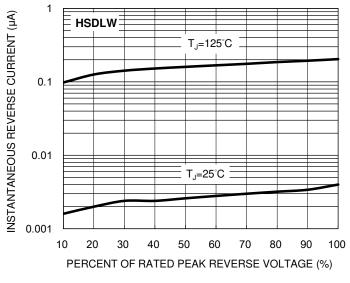
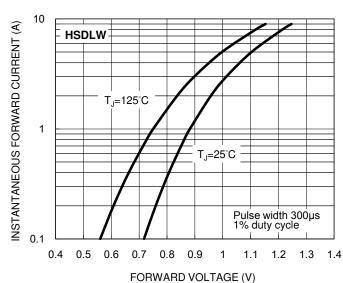


Fig.4 Typical Forward Characteristics





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.5 Typical Reverse Characteristics

INSTANTANEOUS REVERSE CURRENT (µA) **HSGLW** T_{.1}=125°C 0.1 0.01 T_J=25°C 0.001 20 80 100 10 30 40 50 60 70 90 PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

Fig.6 Typical Forward Characteristics

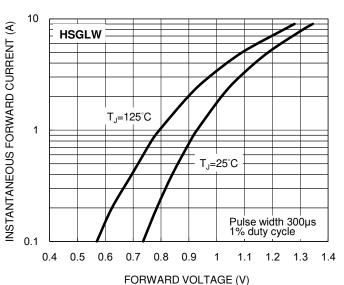


Fig.7 Typical Reverse Characteristics

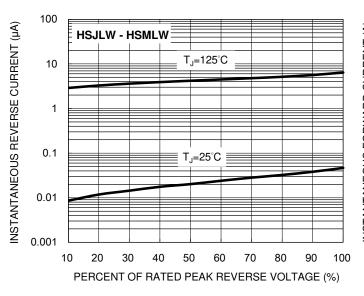
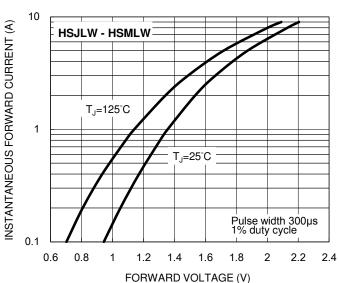
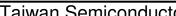


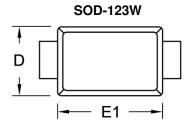
Fig.8 Typical Forward Characteristics

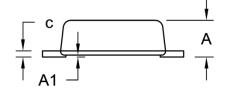


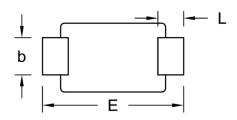




PACKAGE OUTLINE DIMENSIONS

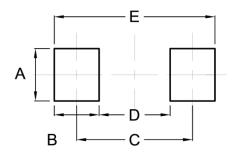






DIM. Unit		(mm)	mm) Unit (inch)	
DIIVI.	Min.	Max.	Min.	Max.
Α	0.90	1.02	0.035	0.040
A1	0.00	0.10	0.000	0.004
b	0.90	1.05	0.035	0.041
С	0.10	0.22	0.004	0.009
D	1.70	1.90	0.067	0.075
E	3.60	3.80	0.142	0.150
E1	2.60	2.90	0.102	0.114
L	0.50	0.85	0.020	0.033

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.40	0.055
В	1.20	0.047
С	3.10	0.122
D	1.90	0.075
E	4.30	0.169

MARKING DIAGRAM



P/N = Marking Code ΥW = Date Code F = Factory Code

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